L Number	Hits	Search Text	DB	Time stamp
1	231461	(cihp or die or device) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/29 11:03
2	239600	(chip or die or device) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/29 13:11
3	6407	<pre>((chip or die or device) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)) and ((grind or grinding or polish or polishing ro cmp) same (chip or die or encapsulant or encapsulation or mold or molding))</pre>	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 12:50
4	6407	1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 13:12
5	6333		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 12:50
	3477	((chip or die or device) and (@ad<20010427) and (encapsulant or encapsulation or mold or molding)) and ((grind or grinding or polish or polishing or cmp) with (chip or die or encapsulant or encapsulation or mold or molding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 11:15
7	663	e · ·	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 11:16
8	710		USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 12:52
9	1	(batch adj transfer) and ((grind or grinding or polish or polishing or cmp) same (chip or die or encapsulant or encapsulation or mold or molding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/29 12:51
10	5858	(batch or transfer) and ((grind or grinding or polish or polishing or cmp) same (chip or die or encapsulant or encapsulation or mold or molding))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/06/29 12:51
11	4221	((batch or transfer) and ((grind or grinding or polish or polishing or cmp) same (chip or die or encapsulant or encapsulation or mold or molding))) and (@ad<20010427)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/29 12:52

12	1162	[//hatch or transfort and //arind or	USPAT;	2004/06/29
12	1162	1 , , ,	US-PGPUB;	12:52
		grinding or polish or polishing or cmp)		12.52
		same (chip or die or encapsulant or	EPO; JPO;	
		encapsulation or mold or molding))) and	DERWENT;	
1		(@ad<20010427)) and (semiconductor or ic)	IBM_TDB	
13	875	` ` ` ` `	USPAT;	2004/06/29
		grinding or polish or polishing or cmp)	US-PGPUB;	12:53
		same (chip or die or encapsulant or	EPO; JPO;	
		encapsulation or mold or molding))) and	DERWENT;	
		(@ad<20010427)) and (semiconductor or	IBM_TDB	
		ic)) not ((((chip or die or device) and	_	
		(@ad<20010427) and (encapsulant or		
		encapsulation or mold or molding)) and		
		((grind or grinding or polish or		
		polishing or cmp) with (chip or die or		
		encapsulant or encapsulation or mold or		
i		molding))) and semiconductor)		
14	1943	(different near (chips or dies or	USPAT;	2004/06/29
		devices)) and (@ad<20010427) and	US-PGPUB;	13:12
		(encapsulant or encapsulation or mold or	EPO; JPO;	
		molding)	DERWENT;	
			IBM TDB	
15	24	((different near (chips or dies or	USPAT;	2004/06/29
		devices)) and (@ad<20010427) and	US-PGPUB;	13:14
		(encapsulant or encapsulation or mold or	EPO; JPO;	
		molding)) and 257/778.ccls.	DERWENT;	
			IBM TDB	
16	24	(((different near (chips or dies or	USPAT;	2004/06/29
		devices)) and (@ad<20010427) and	US-PGPUB;	13:13
		(encapsulant or encapsulation or mold or	EPO; JPO;	13.13
		molding)) and 257/778.ccls.) and	DERWENT;	
		(@ad<20010427)	IBM TDB	
17	172	·	USPAT;	2004/06/29
- '		devices)) and (@ad<20010427) and	US-PGPUB;	13:15
<u> </u>		(encapsulant or encapsulation or mold or	EPO; JPO;	13.13
		molding)) and flip	DERWENT;	
		· · · · · · · · · · · · · · · · · · ·	IBM TDB	
18	152	(((different near (chips or dies or	USPAT;	2004/06/29
	102	devices)) and (@ad<20010427) and	US-PGPUB;	13:15
		(encapsulant or encapsulation or mold or	EPO; JPO;	13.13
		molding)) and flip) not ((different near	DERWENT;	
		(chips or dies or devices)) and	IBM TDB	
		(@ad<20010427) and (encapsulant or		
		encapsulation or mold or molding)) and		
		257/778.ccls.)		
		201/110.0013.]		